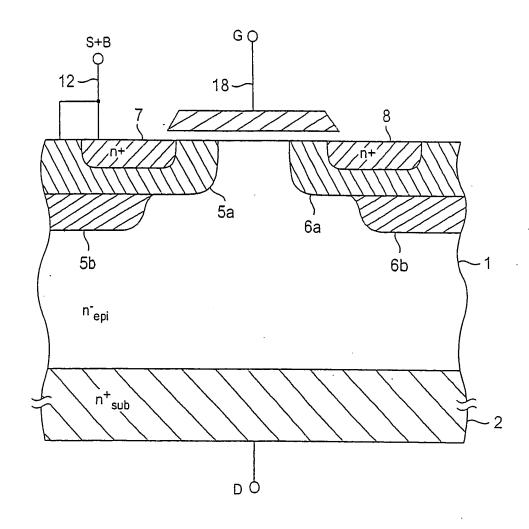
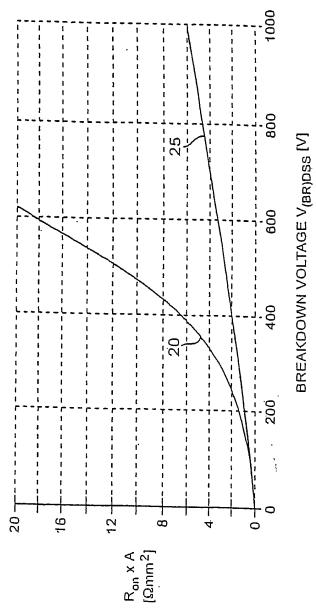


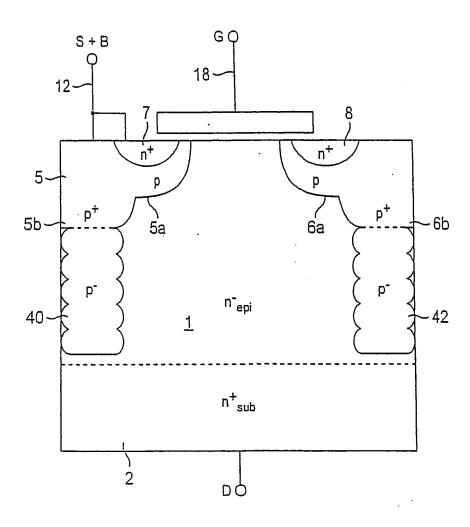
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CONVENTIONAL MOSFET

FIG. 1 (PRIOR ART)





THE DOPANT DISTRIBUTION OF A HIGH VOLTAGE VERTICAL DMOS TRANSISTOR WITH A RELATIVELY LOW ON-RESISTANCE

FIG. 3

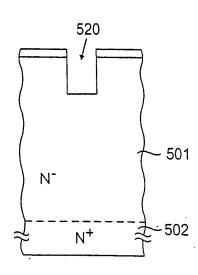
(PRIOR ART)

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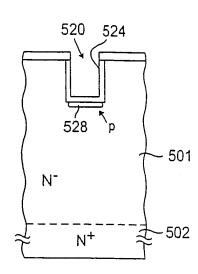
- 1. EPITAXIAL DEPOSITION
- 2. FORMATION OF THE TRENCH ETCH STOP LAYER
- 3. MASK AND ETCH THE TRENCH ETCH STOP LAYER
- 4. TRENCH ETCH

FIG. 4(a)



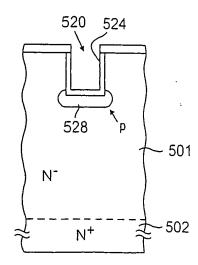
- 5. GROW THIN OXIDE LAYER IN THE TRENCH
- 6. IMPLANT THE DOPANT

FIG. 4(b)



- 7. PERFORM A HIGH TEMPERATURE DIFFUSION
- 8. ETCH THE OXIDE AT THE BOTTOM OF THE TRENCH

FIG. 4(c)





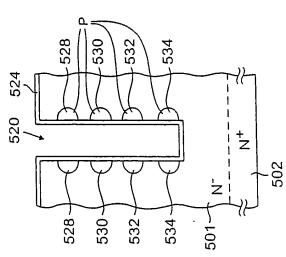
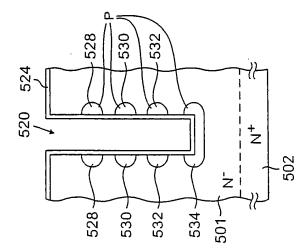
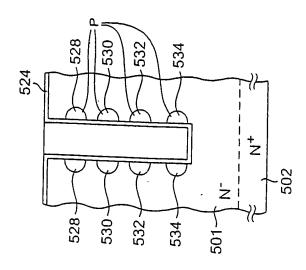


FIG. 4(d)



9. REPEAT THE DOPING AND ETCH STEPS AS MANY TIMES AS REQUIRED 10. DOPE THE REGION FURTHEST FROM THE SURFACE



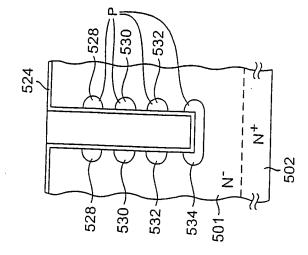


FIG. 4(e)

11. FILL THE TRENCH12. PLANARIZE THEWAFER SURFACE



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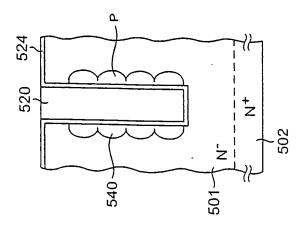
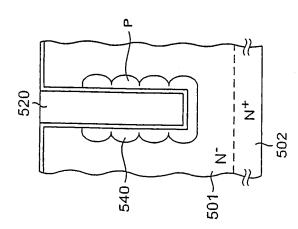


FIG. 4(f)



13. PERFORM A HIGH TEMPERATURE DIFFUSION STEP